

ABSTRACT

The following is a description of a stacked pad 15 for chemical mechanical polishing and/or planarizing substrates. In one embodiment, the stacked pad includes
5 a top pad 20 and a subpad 40 where the modulus of the top pad 20 substantially equals the modulus of the subpad 40. Also presented are methods of using the stacked pad 15 which include methods of chemical mechanical polishing and/or planarization, and products of using the stacked pad.